

**Integrated chip package structure using silicon substrate and method of
manufacturing the same**

Appl. No. : 10/755,042 Confirmation No. : 8665
Applicant : Mou-Shiung Lin et al.
Filed : January 9, 2004
TC/A.U. : 2815
Examiner : JACKSON JR, JEROME
Docket No. : MEGP0004USA1
Customer No. : 27765

Commissioner for Patents
P.O. Box 1450
Alexandria VA 22313-1450

5 **AMENDMENT AND REQUEST FOR CONTINUED EXAMINATION**

Sir:

In response to the Office action of January 4, 2008, please amend the above-identified application as follows:

10 **Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 10 of this paper.